Materials Declaration

Package	LFCSP
Body Size	4 X 4
LeadCount	16
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	1.19 E-02	345275
Epoxy Resin	10	1.40 E-03	40621
Phenol Resin	5	7.01 E-04	20310
Subtotal		1.40 E-02	406205

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.72 E-02	499265
Fe	2.35	4.15 E-04	12034
P	0.03	5.30 E-06	154
Zn	0.12	2.12 E-05	614
Subtotal		1.77 E-02	512066

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.20 E-04	9274

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.23 E-04	3576

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.58 E-04	10361

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.72 E-03	49872

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	2.24 E-04	6484
Resin	25	7.46 E-05	2161
Subtotal		2.98 E-04	8646

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S.

Package Totals

Weight (g)	PPM
3.45 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Materials Declaration

Package	LFCSP
Body Size	4 X 4
LeadCount	16
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	1.19 E-02	345275
Epoxy Resin	10	1.40 E-03	40621
Phenol Resin	5	7.01 E-04	20310
Subtotal		1.40 E-02	406205

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.72 E-02	499265
Fe	2.35	4.15 E-04	12034
P	0.03	5.30 E-06	154
Zn	0.12	2.12 E-05	614
Subtotal		1.77 E-02	512066

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.20 E-04	9274

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.05 E-04	3039
Pb	15	1.85 E-05	536
Subtotal		1.23 E-04	3576

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.58 E-04	10361

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.72 E-03	49872

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	2.24 E-04	6484
Resin	25	7.46 E-05	2161
Subtotal		2.98 E-04	8646

Package Totals

Weight (g)	PPM
3.45 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES